IN THE SPECIFICATION:

Please replace paragraph number **[0001]** with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 09/847,556, filed May 2, 2001, ~~pending~~ now U.S. Patent 6,585,097, issued July 1, 2003.

Please replace paragraph number **[0003]** with the following rewritten paragraph:

[0003] State of the Art: In the manufacture and testing of semiconductor devices, such as bare semiconductor die or packaged semiconductor die, the semiconductor devices, being either packaged or bare semiconductor die, are transferred through various locations and experience extensive handling. In performing specific tests or particular manufacturing operations, it is often required to separate a single semiconductor device from a plurality of similar semiconductor devices. This act of separation can and may be typically referred to as ~~"singulation".~~ "singulation." The singulation of a semiconductor device may be accomplished by various means. However, singulation is generally accomplished by implementing an actuating member to stop, advance, or otherwise manipulate a semiconductor device in some manner with respect to one or more adjacent semiconductor devices. The actuating member is often one or more stop members in the form of pins, rods, cams or lever arms motivated by a pneumatic cylinder. In some alternative designs a solenoid or hydraulic cylinder may be employed.

Please replace paragraph number **[0028]** with the following rewritten paragraph:

[0028] Referring now to drawing Figs. 4A through 4C a portion of an automated handler 80 is shown wherein flexible membranes or bladders, similar to those described above, are employed. The handler 80 includes an input location 82, such as a hopper or magazine, for loading a plurality of semiconductor devices 84. The semiconductor devices 84 dispense serially onto an inclined track 86 which feeds the semiconductor devices to a singulation device 88 such as by means of gravity. As the semiconductor devices 84 pass along the track 86 adjacent the singulation device 88, a flexible membrane or bladder 90, similar to that described above, is

actuated such that it contacts and immobilizes the semiconductor device 84 furthest down the track 86 as seen in drawing FIG. 4A. Immobilization of the semiconductor device 84 adjacent the singulation device 88 also causes all of the upstream semiconductor devices to stop as well. A second flexible membrane or bladder 92 then engages the semiconductor device 84 directly adjacent and upstream from the first immobilized semiconductor device 84 as shown in drawing ~~FIG.4B~~ FIG. 4B. Thereafter, the first flexible membrane 90 is disengaged allowing the first semiconductor device 84 to advance while the remaining semiconductor devices 84 are held in place by the immobilization of the second semiconductor device 84 via the second flexible membrane 92. While stopped by the first flexible membrane 90, the first semiconductor device 84 may be subjected to a testing or manufacturing process. Or alternatively, following the release of the first semiconductor device 84 , it may be stopped by a third flexible membrane (not shown) at a predetermined distance down the track 86 to be subjected to a specified manufacturing or testing process. Subsequent the release of the first semiconductor device 84 , the second semiconductor device 84 may be released and advanced until it is contacted and immobilized by the first flexible membrane 90 and the cycle will continue.